

In the Claims:

1. (Currently Amended) A method of cleaning a hole formed in an organic inter-level dielectric (ILD), the hole having sidewalls and a bottom, the organic ILD disposed on a semiconductor substrate, the method comprising:  
  
performing a radio frequency (RF) sputter clean of the hole; and  
  
performing an anisotropic, ion enhanced ~~organic~~ etch of organic material deposited in the hole at least partially during the sputter clean,  
  
whereby organic material displaced from the sidewalls to the bottom of the hole by the sputter clean is removed by the anisotropic organic etch.
2. (Currently Amended) The method of claim 1, wherein the ion enhanced ~~organic~~ etch of the organic material comprises a nitrogen plasma.
3. (Currently Amended) The method of claim 24-1, wherein the RF sputter clean comprises an argon plasma.
4. (Currently Amended) The method of claim 24-1, wherein the RF sputter clean comprises a helium plasma.
5. (Canceled)
6. (Currently Amended) The method of claim 24-5, wherein the anisotropic ion enhanced etch of the organic material comprises ~~plasma~~ is a nitrogen plasma.

7. (Currently Amended) The method of claim 24-1, wherein the organic etch of the organic material is ion enhanced with an RF bias of between about 0 watts and about 500 watts.
8. (Currently Amended) The method of claim 24-1, wherein the RF sputter clean and the organic etch are performed over about the same time interval.
9. (Original) The method of claim 1, wherein the hole is part of an interconnect structure, wherein a conductive layer is disposed at a bottom of the hole, and wherein the RF sputter clean removes a surface oxide formed on the conductive layer.
10. (Original) A method of cleaning an interconnect structure formed in an organic ILD, the structure comprising a hole having a bottom and sidewalls, the structure disposed on a semiconductor substrate, the method comprising:
- forming a plasma over the interconnect structure, the plasma comprising a physical etch component and an ion enhanced chemical etch component;
  - directing the plasma toward the interconnect structure;
  - sputter cleaning the bottom of the hole with the physical etch component; and
  - anisotropically removing organic material from the bottom of the hole with the chemical etch component.
11. (Original) The method of claim 10, wherein the chemical etch component comprises nitrogen.

12. (Original) The method of claim 10, wherein the physical etch component comprises argon.
13. (Original) The method of claim 10, wherein the physical etch component comprises helium.
14. (Canceled)
15. (Original) The method of claim 10, wherein the chemical etch is ion enhanced with an RF bias of between about 0 watts and about 500 watts.
16. (Currently Amended) A method of forming an interconnect through an organic ILD, the method comprising:
- forming a lower conductive layer on a semiconductor substrate;
  - forming the organic ILD on the lower conductive layer;
  - etching a hole through the organic ILD down to the lower conductive layer;
  - performing an RF sputter clean of a bottom of the hole;
  - performing an anisotropic, ion enhanced chemical ~~organic~~ etch of organic ILD material deposited in the hole, wherein the etch is performed at least partially during the RF sputter clean;
  - forming a plug in the hole; and
  - forming an upper conductive layer on the organic ILD and the plug.

17. (Original) The method of claim 16, wherein said RF sputter clean comprises using an argon plasma.
18. (Original) The method of claim 16, wherein said RF sputter clean comprises using a helium plasma.
19. (Currently Amended) The method of claim 16, wherein said ~~organic~~ etch of organic ILD material comprises using a nitrogen plasma.
20. (Canceled)
21. (Currently Amended) The method of claim 26-20, wherein the anisotropic ion enhanced chemical etch comprises using ~~plasma~~ is a nitrogen plasma.
22. (Original) The method of claim 16, further comprising:  
forming a lower cap layer on the lower conductive layer before the forming of the organic ILD layer; and  
forming an upper cap layer on the organic ILD layer,  
wherein the etching of the hole further comprises etching through the upper cap layer and lower cap layer.
23. (Original) The method of claim 16, further comprising forming a liner in the hole before the forming of the plug.

24. (New) A method of cleaning a previously etched hole formed in an organic inter-level dielectric (ILD), the hole having a sidewall surface defined by said organic ILD and a bottom comprising a layer of surface oxide formed during the etching of said hole, the organic ILD disposed on a semiconductor substrate, the method comprising:

displacing organic ILD particles from said sidewall surface and depositing said displaced organic ILD particles at said bottom of said hole while performing a radio frequency (RF) sputter clean of the hold to remove said surface oxide at the bottom of said hole; and

removing organic particles displaced from the sidewalls and deposited at the bottom of the hole during the sputter clean by performing an anisotropic, ion enhanced etch of the hole during at least a portion of the sputter clean.

25. (New) A method of cleaning an interconnect structure formed in an organic ILD, the structure comprising a hole having a bottom comprising a layer of surface oxide deposited during the forming of said hole and a sidewall surface defined by said organic ILD, the structure disposed on a semiconductor substrate, the method comprising:

forming a plasma over the interconnect structure, the plasma comprising a physical etch component and an ion enhanced chemical etch component;

directing the plasma toward the interconnect structure;

displacing organic particles from said organic ILD sidewall surface and depositing said displaced particles at said bottom of said hole while sputter cleaning the bottom of the hole with the physical etch component to remove said surface oxide on said bottom; and

anisotropically removing said deposited organic ILD particles from the bottom of the hole with the chemical etch component.

26. (New) A method of forming an interconnect through an organic ILD, the method comprising:

- forming a lower conductive layer having a top surface on a semiconductor substrate;

- forming the organic ILD on the lower conductive layer;

- etching the organic ILD down to the lower conductive layer to define a hole through said ILD comprising a sidewall surface of said organic ILD and a bottom comprising a layer of oxide on the top surface of said lower conductive layer, said layer of oxide formed during said etching step;

- displacing particles from said sidewall surface of said organic ILD and depositing said displaced particles at said bottom of said hole while performing an RF sputter clean of the hole to remove said surface oxide on said exposed surface of said lower conductive layer;

- performing an anisotropic, ion enhanced chemical etch of organic ILD material in the hole during at least a portion the RF sputter clean to remove said deposited displaced particles;

- forming a plug in the hole; and

- forming an upper conductive layer on the organic ILD and the plug.

27. (New) The method of claim 24 wherein the hole is part of an interconnect structure and wherein a conductive layer is disposed at the bottom of the hole.